

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

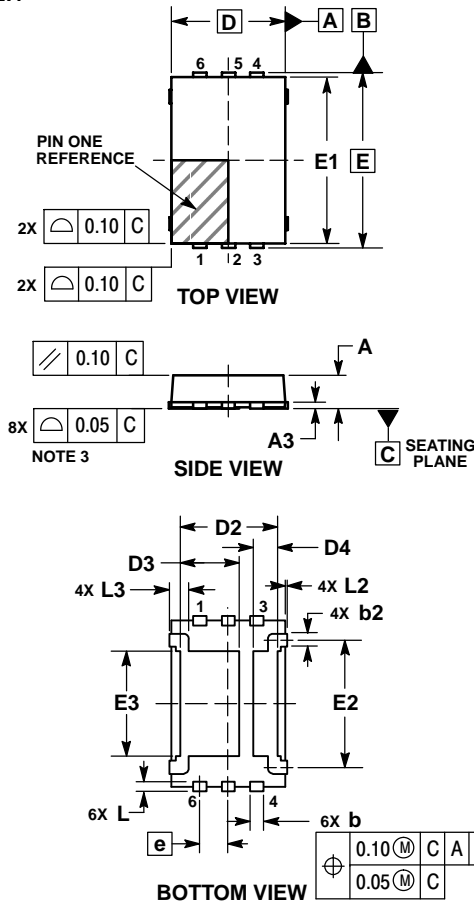
ON Semiconductor®



SCALE 2:1

### WDFN6 2.6x4.0, 0.65P, Dual Flag CASE 511BZ ISSUE B

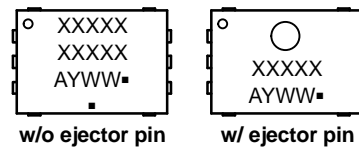
DATE 02 NOV 2016



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. PROFILE TOLERANCE APPLIES TO THE EXPOSED PADS AS WELL AS THE LEADS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.80
A3	0.10	0.25
b	0.25	0.40
b2	0.15	0.30
D	2.60	BSC
D2	2.075	2.375
D3	1.20	1.50
D4	0.40	0.70
E	4.00	BSC
E1	3.80	REF
E2	2.95	3.05
E3	2.25	2.55
e	0.65 BSC	
L	0.12	0.32
L2	---	0.10
L3	---	0.55

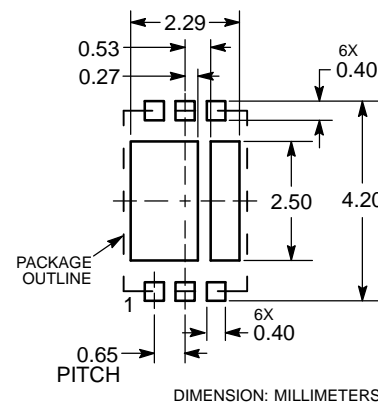
#### GENERIC MARKING DIAGRAM\*



- XXXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)  
\*This information is generic. Please refer to device data sheet for actual part marking.

#### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	WDFN6 2.6X4.0, 0.65P, DUAL FLAG	<b>PAGE 1 OF 2</b>

